## **nse**

# High-Voltage Switcher for

## NCP10670B, NCP10671B, NCP10672B

The NCP1067X products integrate a fixed frequency current mode controller with a 700 V MOSFET. Available in a SOIC 7 package, the NCP1067X offer a high level of integration, including soft start, frequency jittering, short circuit protection, skip cycle, ramp compensation, and a Dynamic Self Supply (eliminating the need for an auxiliary winding).

During nominal load operation, the NCP1067X switches at one of the available frequencies (60 or 100 kHz). When the output power demand diminishes, the IC automatically enters into a skip mode to reduce the standby consumption down.

Protection features include: a timer to detect an overload or a short circuit event, Overvoltage Protection with auto recovery.

For improved standby performance, the connection of an auxiliary winding or supplying the IC from the output, stops the DSS operation and helps to reduce input power consumption below 25 mW at high line.

NCP1067x can be seamlessly used both in non isolated and in isolated topologies.

#### **Features**

Built in 700 V MOSFET with  $R_{DS(on)}$  of 34  $\Omega$  (NCP10670/1) and 12 Ω (NCP10672) Large Creepage Distance Between High Voltage Pins Current Mode Fixed Frequency Operation – 60 or 100 kHz Fixed Ramp Compensation Direct Feedback Connection for Non isolated Converter Skip Cycle Operation at Low Peak Currents Only Dynamic Self Supply: No Need for an Auxiliary Winding Internal 4 ms Soft Start Auto Recovery Output Short Circuit Protection with Timer Based Detection Auto



#### **Table 1. PRODUCTS INFOS & INDICATIVE MAXIMUM OUTPUT POWER**

1. Informative values only, with T<sub>amb</sub> = 25 C, T<sub>case</sub> = 100 C, Self supply via Auxiliary winding and circuit mounted on minimum copper area<br>as recommended.

#### **Table 2. SELECTION TABLE**









**Figure 2. Typical Isolated Application (Flyback Converter)**

#### <span id="page-2-0"></span>**PIN DESCRIPTION**



#### **Table 3. TYPICAL APPLICATION**





#### **Table [3](#page-2-0). TYPICAL APPLICATION**



#### **MAXIMUM RATINGS** (All voltages related to GND terminal)



#### **ELECTRICAL CHARACTERISTICS**

(Tj = 25 C, for min/max values Tj =  $-40$  C to +125 C, Vcc = 14 V unless otherwise noted)



#### **ELECTRICAL CHARACTERISTICS**

(Tj = 25 C, for min/max values Tj = -40 C to +125 C, Vcc = 14 V unless otherwise noted) (continued)



26.59494 899 2552 254.594 .90712294 50016 STS--.0018 2 22 .616.EET 26.5949 BP to

26.59494 .907 p. 007 Tu-(+15036Tj /TT4 110.849 .12 0 TD <00ef2294 50016 T373.833 3 Tm

#### <span id="page-8-0"></span>**ELECTRICAL CHARACTERISTICS**

(Tj = 25 C, for min/max values Tj = −40 C to +125 C, Vcc = 14 V unless otherwise noted) (continued)



#### **TYPICAL CHARACTERISTICS** (continued)





Figure 11. I<sub>CC1</sub> (10672\_60k) vs. Temperature Figure 12. I<sub>CC1</sub> (10672\_100k) vs. Temperature



Figure 13. I<sub>IPK(s. TemperaturewwwPK(s. TemperatureI</sub>





Figure 9. I<sub>CC1 (10670\_60k)</sub> vs. Temperature Figure 10. I<sub>CC1 (NCP10670\_100k)</sub> vs. Temperature







#### **TYPICAL CHARACTERISTICS** (continued)



Figure 17. I<sub>freeze10671</sub> vs. Temperature **Figure 18. Iffreeze10672** vs. Temperature











Figure 19. R<sub>DS(on)10670/1</sub> vs. Temperature Figure 20. R<sub>DS(on)10672</sub> vs. Temperature



**Figure 21. f<sub>OSC60</sub> vs. Temperature Figure 22. f<sub>OSC100</sub> vs. Temperature** 



#### **TYPICAL CHARACTERISTICS** (continued)

















#### **APPLICATION INFORMATION**

#### **INTRODUCTION**

The NCP1067X offers a complete current mode control solution. The component integrates everything needed to build a rugged and cost effective Switch Mode Power Supply (SMPS) featuring low standby power. The Quick Selection Table is on details the differences between references, mainly peak current setpoints,  $R_{DS(on)}$  value and operating frequency.

*Current−mode operation:* the controller uses current mode control architecture.

*700 V – \_ Power MOSFET:* Due to **onsemi** Very High Voltage Integrated Circuit technology, the circuit hosts a high voltage power MOSFET featuring a 34 or 12  $\Omega$  $R_{DS(on)} - T_J = 25$  C. This value lets the designer build a power supply up to 7.8 W operated on universal mains. An internal current source delivers the startup current, necessary to crank the power supply.

*Dynamic Self−Supply:* Due to the internal high voltage current source, this device could be used in the application without the auxiliary winding to provide supply voltage. *Short circuit protection:* by permanently monitoring the COMP line activity, the IC is able to detect the presence of a short circuit, immediately reducing the output power for a total system protection. A t<sub>SCP</sub> timer is started as soon as the COMP current is below threshold,  $I_{COMP}$  f<sub>ault</sub>, which indicates the maximum peak current. If at the end of this timer the fault is still present, then the device enters a safe, auto recovery burst mode, affected by a fixed timer recurrence, t<sub>recovery</sub>. Once the short has disappeared, the controller resumes and goes be sWo

#### **Fault Condition – Short-circuit on V<sub>CC</sub>**

In some fault situations, a short circuit can purposely occur between V<sub>CC</sub> and GND. In high line conditions  $(V_{\text{HV}} = 370 \text{ V}_{\text{DC}})$  the current delivered by the startup device will seriously increase the junction temperature. For instance, since  $I<sub>start1</sub>$  equals 4 mA (the min corresponds to the highest  $T_j$ ), the device would dissipate  $370 \cdot 4$  m 1.48 W. To avoid this situation, the controller includes a novel circuitry made of two startup levels, Istart1 and Istart2. At power

#### **Auto−recovery Over Voltage Protection**

The particular NCP1067X arrangement offers a simple way to prevent output voltage runaway when the optocoupler fails. As Figure 36 shows, a comparator monitors the  $V_{CC}$  pin. If the auxiliary pushes too much voltage into the C<sub>VCC</sub> capacitor, then the controller considers an OVP situation and stops the internal drivers. When an OVP occurs, all switching pulses are permanently disabled. After t<sub>recovery</sub> delay, it resumes the internal drivers. If the failure symptom still exists, e.g. feedback opto

#### **Soft−start**

The NCP1067X features a 4 ms soft start which reduces the power on stress but also contributes to lower the output overshoot. Figure 38 shows a typical operating waveform. The NCP1067X features a novel patented structure which offers a better soft start ramp, almost ignoring the start up pedestal inherent to traditional current mode supplies:



**Figure 38. The 4 ms Soft−start Sequence**

#### *Ipk Reduction*

The internal peak current set point is following the COMP current information until its level reaches IFreeze. Below this value, the peak current setpoint is frozen to 30% of the  $I_{IPK(0)}$ . This value is reached at a COMP current level

of I<sub>COMPskip</sub> (120 µA typically). Below this point, if the output power continues to decrease, the part enters skip cycle for the best performance in no load conditions. Figure 40 depict the adopted scheme for the part.



Figure 40. I<sub>IPK</sub> Set-point is Frozen at Lower Power Demand

#### *Feedback and Skip*

Figure 41 depicts the relationship between COMP pin voltage and current. The COMP pin operates linearly as the absolute value of COMP current  $(I_{COMP})$  is above 40  $\mu$ A. In

this linear operating range, the dynamic resistance is 17.7 k $\Omega$  typically ( $R_{COMP(up)}$ 

Figure 42 depicts the skip mode block diagram. When the COMP current information reaches I<sub>COMPskip</sub>, the internal clock to set the flip flop is blanked and the internal consumption of the controller is decreased. The hysteresis of internal skip comparator is minimized to lower the ripple of the auxiliary voltage for  $V_{CC}$  pin and  $V_{OUT}$ 

#### *FB pin function*

The FB pin is used in non isolated SMPS application only. Portion of the output voltage is connected into the pin. The voltage is compared with internal  $V_{REF}$  (3.3 V) using 3. Lateral MOSFETs have a poorly doped body diode which naturally limits their ability to sustain the avalanche. A traditional RCD clamping network shall thus be installed to protect the MOSFET. In some low power applications, a simple capacitor can also be used since

$$
V_{\text{drain,max}} = V_{\text{in}} + N (V_{\text{out}} + V_{\text{f}}) + I_{\text{peak}} \sqrt{\frac{L_{\text{f}}}{C_{\text{tot}}}}
$$
 (eq. 5)

where  $L_f$  is the leakage inductance,  $C_{tot}$  the total capacitance at the drain node (which is increased by the capacitor you will wire between drain and source), N the  $N_P: N_S$  turn ratio,  $V_{out}$  the output voltage, *Vf* the secondary diode forward drop and finally, *Ipeak* the maximum peak current. Worse case occurs when the SMPS is very close to regulation, e.g. the *Vout* target is almost reached and *Ipeak* is still pushed to the maximum. For this design, we have selected our maximum voltage around 650 V (at *Vin* = 375 Vdc). This voltage is given by the *RCD* clamp installed from the drain to the bulk voltage. We will see how to calculate it later on.

4. Calculate the maximum operating duty cycle for this flyback converter operated in CCM:

$$
d_{max} = \frac{N (V_{out} + V_f)}{N (V_{out} + V_f) + V}
$$

#### **MOSFET Protection**

As in any Flyback design, it is important to limit the drain excursion to a safe value, e.g. below the MOSFET BVdss

which is 700 V. Figure 47 *a−b−c* present possible implementations:

$$
\frac{3}{5}\bigg\|\xi
$$

**Figure 47. Different Options to Clamp the Leakage Spike**

#### **SOIC8 MISSING PIN 3** CASE 751EV

ISSUE O

**SCALE 1:1**



 $\bigoplus$  0.12 $\bigcirc$ 



**SEATING PLANE**

- NOTES:<br>
1. DIMENSIONING AND TOLERANCING PER ASME<br>
2. CONTROLLING DIMENSION: MILLIMETERS.<br>
3. DIMENSION DOES NOT INCLUDE DAMBAR<br>
1. DIMENSION DOES NOT INCLUDE DAMBAR<br>
PROTRUSION. ALLOWABLE PROTRUSION SHALL<br>
BE 0.10mm IN EXC
- 
- 6. A1 IS DEFINED AS THE VERTICAL DISTANCE FROM THE SEATING PLANE TO THE LOWEST POINT ON THE PACKAGE BODY.



**e** | 1.27 BSC

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